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## (54) SEMICONDUCTOR MEASURING DEVICE

## (57) Abstract:

**PURPOSE:** To vacuumize a wafer through a chuck to easily fix the wafer, by interposing an insulating sheet, in which minute holes are formed corresponding to the positions of grooves on the chuck surface, between the chuck and the wafer.

**CONSTITUTION:** An insulating sheet 3, in which holes 2 fully smaller than the width of grooves 4 on the surface of a chuck 6 are numerous formed corresponding to the positions of the grooves 4 for fixing a semiconductor wafer 1 in a vacuum state on the surface of the chuck 6, is interposed between the surface of the chuck 6 and the wafer 1 so as to be capable of being assembled and disassembled. The wafer 1 is then vacuumized through the chuck 6. Hence, the wafer 1 can be easily fixed.

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